ASSOCIATION CONNECT	Material Composit © Copyright 2005. IPC, international and Pan-Ar	tion Dec Bannockbi nerican coj	<b>laration</b> urn, Illinois. A pyright conve	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration	tion of th encompa	ne substances asses all lowe	within the r level ma	manufactur terials for wl	er listed ite hich the m	em. Note: i anufacture	if the item is an as r has engineering	sembly with low responsibility.	
752-21.1					Form Type Distribute	Form Type * Declaration Class * Distribute Class 6 - RoHS Yes/No, Homogeneous Mat					eous Materia	rials and Mfg Information				
upplier Infor	mation															
ompany name*		Company unique ID				Unique ID Authority					Response Date*					
nsemi												2025-05-11				
ontact Name			Title - Contact				Phone - Contact*					Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorized Repre	sentative*		Title - Representative				Phone - Representative*				Email - Representative*					
roduct-Env-Stev	vards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Reques	Requester Item Number Mfr Iter		em Number Mfr Item Name				Effective Date	e Vers	ion 1	Manufacturing Site		v	Veight*	UOM	Unit Type	
		NOIP1SN0480A-STI P		PYTHON480 1/3.6", BW_CRA1.65		1.65	2025-05-11		,	TWU		3	8.3603	mg	Each	
lanufacturinș	g Proccess Information	n		·										I	l	
Termina	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020		J-STD-020 MS	L Rating	Peak Process		s Body Temperature Max Time at Peak		Temperatu	ire Numb	per of Reflow Cyc	eles		
SnAgCu		C	CU Alloy 4			<b>245</b> C		C	30		second	ls 3				
omments																
or more informa	tion regarding material com	position p	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.6894	mg	Supplier	Silicon (Si)	7440-21-3		6.6894	mg
Glass Attach Epoxy	0.0053	mg		Miscellaneous	trade secret		0.0007	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.0046	mg
Glass Lid /Cap	29.3747	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		2.9375	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		1.4687	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		1.4687	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.9375	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		1.4687	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		19.0936	mg
Metal Shielding	0.0483	mg	Supplier	Copper (Cu)	7440-50-8		0.0002	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0481	mg
RDL	0.053	mg	В	Nickel (Ni)	7440-02-0		0.0328	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.0001	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0198	mg
Solder Ball	2.1563	mg	Supplier	Silver (Ag)	7440-22-4		0.0647	mg
			Supplier	Tin (Sn)	7440-31-5		2.0808	mg
			Supplier	Copper (Cu)	7440-50-8		0.0108	mg
Substrate and Solder Mask	0.0333	mg	Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.0033	mg
			Supplier	9-Phenylacridine	602-56-2		0.0017	mg
			Supplier	2-Propenoic acid	1245638-61-2		0.0033	mg
			Supplier	3-Methoxy-1-butanol	2517-43-3		0.0083	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0083	mg
			Supplier	1-Methoxy-2-propyl acetate (MPA)	108-65-6		0.0083	mg